SI	PE	IFI	Δ٦		M	2
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CUSTOMER . CDE012

SAMPLE CODE . SH320240T023-IHB

MASS PRODUCTION CODE . PH320240T023-IHB

SAMPLE VERSION . 02

SPECIFICATIONS EDITION . 006

DRAWING NO. (Ver.) . JLMD-PH320240T023-IHB_002

PACKAGING NO. (Ver.) . JPKG-PH320240T023-IHB_002

Customer Approved

Date:

POWERTIP 2017.04.24 JS RD APPROVED

Approved	Checked	Designer
 	張久慧	劉進

☐ Preliminary specification for design input

Specification for sample approval

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History of Version

Date	Ver.	Edi.	Description	Page	Design by
08/29/2016	01	001	New Drawing	-	劉進
09/09/2016	01	002	Modify Specs.(Drawing)	-	劉進
12/02/2016	01	003	New Sample Update VCC & ICC Update Touch Panel Pin	5 14,16,Appendix	劉進
02/12/2017	02	004	Second Sample: Modify Backlight Characteristics & VCC 's Value	5,6,9	劉進
04/12/2017	02	005	Update VCC 's Range	5	劉進
04/24/2017	02	006	Modify Backlight V _L & I _L	9	劉進
				>	
		X			

Total: 35 Pages



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Appendix : LCM Drawing Packaging

Note: For detailed information please refer to IC data sheet:

Primacy(TFT LCD): Himax: HX8238-D



1. SPECIFICATIONS

1.1 Features

Item	Standard Value				
Display Resolution	320 * (RGB) * 240 Dots				
LCD Type	a-Si TFT , Normally white , Transmissive type				
Touch panel	4-Wire Resistive Touch Screen				
Screen size(inch)	3.5 inch				
Viewing Direction	6 O'clock				
Color configuration	R.G.B. Vertical Stripe				
Backlight Type	White LED B/L				
Weight					
Interface	24 Bits RGB Interface				
Other	Ur. Nivoses P				
(controller / driver IC)	Himax: HX8238-D				
	THIS PRODUCT CONFORMS THE ROHS OF PTC				
ROHS	Detail information please refer website :				
	http://www.powertip.com.tw/news.php?area_id_view=1085560481/				

1.2 Mechanical Specifications

Item	Standard Value	Unit
Outline Dimension	76.9(W) * 63.9(L) * 4.3(H)	mm

LCD panel

Item		Standard Value	Unit
Active Are	ea	70.08 (W) * 52.56 (L)	mm

Note: For detailed information please refer to LCM drawing.



1.3 Absolute Maximum Ratings

Module

Item	Symbol	Condition	Min.	Max.	Unit	Remark
Power Supply Voltage	VDD	GND=0	-0.3	+5.0	V	
Power Supply Voltage	VCC	GND=0	-0.3	+23.0	V	
Operating Temperature	T _{OP}	-	-20	+70	°C	-
Storage Temperature	T _{ST}	-	-30	+80	°C	

The absolute maximum rating values of this product are not allowed to be exceeded at any times. Should a module be used with any of the absolute maximum ratings exceeded, the characteristics of the module may not be recovered, or in an extreme case, the module may be permanently destroyed.

1.4 DC Electrical Characteristics

Module $Ta = 25^{\circ}C$

Item	Symbol	Condition	Min.	Тур.	Max.	Unit
Power Supply for TFT Panel	VDD	GND=0V	3.0	3.3	3.6	V
Power Supply for Backlight Unit	VCC	GND=0V	5	12	15	V
Input Voltage for TFT Panel	VIH	GND=0V	0.7VDD	ı	VDD	V
input voltage for TFT Farier	VIL	GND=0V	0	ı	0.3VDD	V
Supply Current for TFT Panel	IDD IDD@VDD=3.3V		ı	11	17	mA
Supply Current for Pooklight Unit	ICC	ICC@VCC=5V	ı	100	150	mA
Supply Current for Backlight Unit	100	ICC@VCC=12V	-	50	75	mA
Input Voltage for DWM Cignal	VPH	GND=0V	1.2	-	-	V
Input Voltage for PWM Signal	VPL	GND=0V	-	-	0.4	V
Dimming Clock Rate	fP	GND=0V	5	-	100	KHz

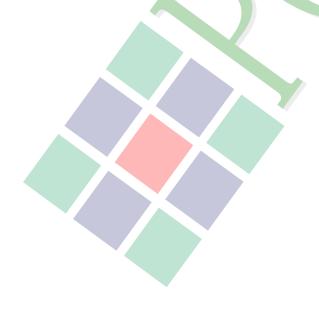




1.5 Optical Characteristics

VDD=3.3V, Ta=25°C

Item		Symbol	Condition	Min.	Тур.	Max.	unit	-
Response tim	ne	Tr + Tf	-	-	40	60	ms	Note2
	Тор	θ+		-	60	-		
Viewing angle	Bottom	θ-	OD > 10	-	60	-	Dog	Note 4
Viewing angle	Left	θL	CR ≥ 10	-	60	-	Deg.	Note4
	Right	θR		-	60	-		
Contrast ration	0	CR	-	500	600	-	-	Note3
	White	Х		0.28	0.33	0.38		
	vvriite	Y	VCC=12V PWM="High" (Duty=100%)	0.33	0.38	0.43	_	
	Red	Х		0.57	0.62	0.67		
Color of CIE		Y		0.32	0.37	0.42		
Coordinate (LCD & B/L & T/P)	Green	Х		0.29	0.34	0.39		
		Y	(Duty=100%)	0.57	0.62	0.67		Nistad
	Dluc	Х		0.09	0.14	0.19		Note1
	Blue	Y		0.04	0.09	0.14		
Average Brightness								
Pattern=white dis	splay	IV	VCC=12V	620	780	-	cd/m ²	
(LCD & B/L & T/	P)*1		PWM="High"					
Uniformity (LCD & B/L & T/	P)*2	ΔΒ	(Duty=100%)	70	-	-	%	





Note 1:

*1 : △B=B(min) / B(max) * 100%

*2 : Measurement Condition for Optical Characteristics:

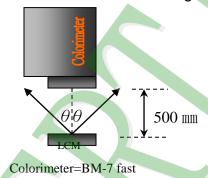
a: Environment: 25°C±5°C / 60±20%R.H, no wind, dark room below 10 Lux at typical lamp current and typical operating frequency.

b : Measurement Distance: $500 \pm 50 \text{ mm}$, $(\theta = 0^{\circ})$

c: Equipment: TOPCON BM-7 fast, (field 1°), after 10 minutes operation.

d: The uncertainty of the C.I.E coordinate measurement ±0.01, Average Brightness ± 4%





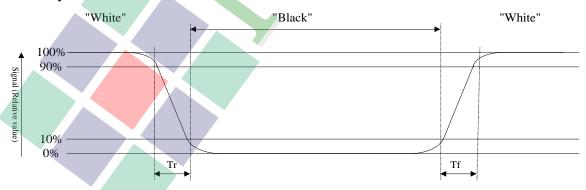
To be measured at the center area of panel with a viewing cone of 1° by Topcon luminance meter BM-7, after 10 minutes operation (module)

Note2: Definition of response time:

The output signals of photo detector are measured when the input signals are changed from "black" to "white" (falling time) and from "white" to "black" (rising time), respectively. The response time is defined as the time interval between the 10% and 90% of Amplitudes.

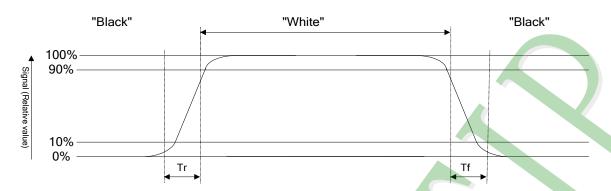
Refer to figure as below:

Normally White





Normally Black



Note3: Definition of contrast ratio:

Contrast ratio is calculated with the following formula

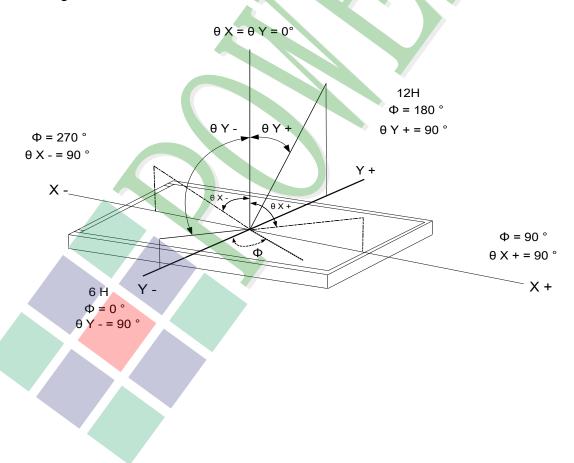
Photo detector output when LCD is at "White" state

Contrast ratio (CR) =

Photo detector output when LCD is at "Black" state

Note4: Definition of viewing angle:

Refer to figure as below:





1.6 Backlight Characteristics

Maximum Ratings

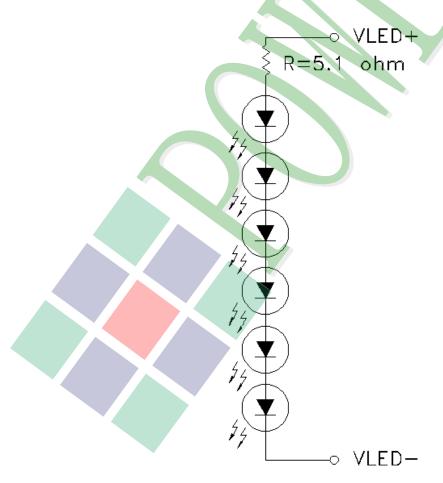
Item	Symbol	Min.	Max.	Unit	Remark
LED Forward Current	l _F	30		mA	One I ED
LED Reverse Voltage	V _R	į	5	V	One LED

Electrical / Optical Characteristics

Ziodinda / Oblica Orial actoricae							
Item	Symbol	Min.	Тур.	Max.	Unit	Remark	
LED Voltage	VL	18	19	19.8	V	Note1	
LED Current	lι	-	20	1	mA	_	
LED life time	-	50000	(-	-	Hr	Note2	

Note 1: The LED Supply Voltage is defined by the number of LED at Ta=25 ℃ and I∟=20 mA.

Note 2: The "LED life time" is defined as the module brightness decrease to 50% original brightness at Ta=25 °C and I∟=20 mA. The LED life time could be decreased if operating I∟ is larger than 20 mA.





1.7 Touch Panel Characteristics

1.7.1 Optical Characteristics

Item	Specification	
1.Transparency	78% Min	

1.7.2 Mechanical Characteristic

Item	Specification
1.Input Method	Finger or stylus pen
2.Hardness of surface	3H -pressure 500g of ,45deg.
3.Activation Force	50gf (TYP. 20gf) less individual point with stylus pen(R0.8)
	Activation force guarantee area:5.0mm inside of Active Area.
4.Linearity Force	100gf less input with stylus pen(R0.8)
	Linearity force guarantee area:3.0mm inside of Active Area.

1.7.3 Electrical Characteristics

Item	Specification				
1.Rated Voltage	DC 5V (DC 7V Max)				
2.Resistance Between	Direction X (Glass side): 300Ω~850Ω				
Terminals.	Direction Y (Film side): 150Ω~550Ω				
3.Insulation Resistance	20 MΩ or more (DC 25V 1min)				
4.Linearity	≤ ± 1.5%				
	Linearity(%)= $\Delta V/$ (EV-SV) *100				
	Δ V: The difference between the ideal voltage and measured				
	voltage on the each measuring line.				
	SV: Voltage of starting Points				
	EV: Voltage of Ending Points				
5.Bouncing	<10ms (Tip R 3.75mm, hardness 10°~20°, silicon rubber,500gf				
	operation: 40 mm/sec)				





1.7.4 Reliability Characteristic

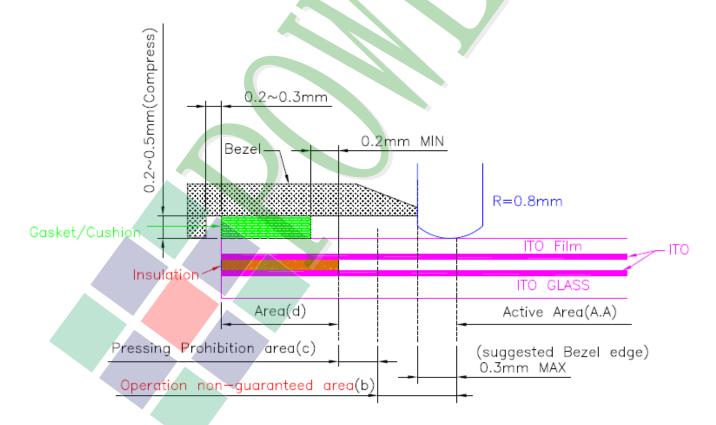
NO	Test Item	Test Condition	Test Result
	Hitting Durability	1,000,000times min.(R 8 mm	Follow 1.7.3 item2 and
1		Silicon Rubber Hardness	item4
		60°250gf 2times/sec).	
2	Pen Sliding Durability	100,000 times min(Tip	Follow 1.7.3 item2 and
2		R0.8mm).	item4.
		ψ9mm steel ball is dropped on	No Crack
3	Impact Resistance	the surface from 30 cm height	
		at 1 time.	
4	Flexible pattern Bending	Bending 3 times by bending	Follow 1.7.3 item2.
4	Resistance	radius R1.0 mm	





1.7.5 Touch Panel Design/Handing Guide

- (1) Keep the gap, for example 0.2 to 0.3mm, between bezel edge and T/P edge.
- The reason is to avoid the bezel edge from contacting T/P surface that may cause "short" with bottom layer
- (2) Insertion a cushion material is recommended.
- (3) The cushion material should be limited on the busbar insulation paste area. If it is over the transparent insulation paste area, a "short" may be occurred.
- (4) Do not to use an adhesive tape to bond it on the front of T/P and hang it to the housing bezel.
- (5) Never expand the T/P top layer (PET Film) like a balloon by internal air pressure. The life of the T/P will extremely decreasing.
- (6) Top layer, PET, dimension is changing base on environment temperature and humidity. Please avoid a stress from housing bezel to top layer, because it may cause "waving".
- (7) The input to the Touch Panel sometimes distorts touch panel itself.
- (8) To use the stylus pen or fingernail sliding at the edge of the housing is prohibited. It would cause the cracking of the ITO coating and damage the touch panel. It also request not to press this area while assembling
- (9) Purpose: In order to prevent accidental use and performance deterioration, please keep the following precautions.



In order to prevent unusual performance degradation and malfunction of a touch panel, please carry out the set case designing and a touch panel assembling method after surely considering the



definition of each area illustrated in above figure.

Area(a): Active area

The active area is guaranteed the position data detectable precision, operation force and other operations. it is strongly recommended to place the operation button or menu keys within the active area. Due to structure, the active area is less durable at the edge or close to the edge.

Area(b): Operation non-guaranteed area

This area does not guarantee a touch panel operation and its function. When this area is pressed, touch panel shows degradation of its performance and durability such as a pen sliding durability becomes about one-tenth compared with the active area (area-(a) as guaranteed area) and its operation force requires about double. About 0.5 mm outside from a boundary of the active area corresponds to this area.

Area(c): Pressing prohibition area

The area which forbids pressing, because an excessive load is applied to a transparent electrode (ITO) and a serious damage is given to a touch panel function by pressing. About 0.5 mm outside from Operation non-guaranteed area.

Area(d): Non-Active area

The area does not activate even if pressed.





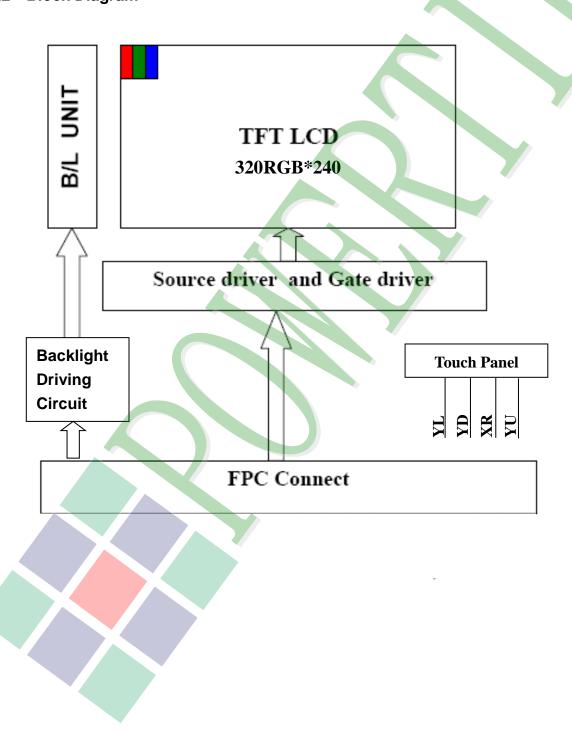
2. MODULE STRUCTURE

2.1 Counter Drawing

2.1.1 LCM Mechanical Diagram

* See Appendix

2.1.2 Block Diagram





2.2 Interface Pin Description

TFT LCM Interface

Pin No.	Symbol	Function
1	GND	Power ground.
2	VDD	Power for Digital Circuit.
3	VDD	Power for Digital Circuit.
4	VCC	Power For LED backlight.
5	VCC	Power For LED backlight.
6	PWM	Shutdown & Dimming control input for backlight. Do not allow this pin to float. "Hi" =100%, "Low" = 0%.
7	GND	Power ground.
8	R0	Red Data.
9	R1	Red Data.
10	R2	Red Data.
11	R3	Red Data.
12	GND	Power ground.
13	R4	Red Data.
14	R5	Red Data.
15	R6	Red Data.
16	R7	Red Data.
17	GND	Power ground.
18	G0	Green Data.
19	G1	Green Data.
20	G2	Green Data.
21	G3	Green Data.
22	GND	Power ground.
23	G4	Green Data.
24	G5	Green Data.
25	G6	Green Data.
26	G7	Green Data.
27	GND	Power ground.
28	B0	Blue Data.
29	B1	Blue Data.



Pin No.	Symbol	Function
30	B2	Blue Data.
31	В3	Blue Data.
32	GND	Power ground.
33	B4	Blue Data.
34	B5	Blue Data.
35	B6	Blue Data.
36	В7	Blue Data.
37	GND	Power ground.
38	HS	Line synchronization signal. Horizontal Sync Input.
39	VS	Frame synchronization signal. Vertical Sync Input.
40	GND	Power ground.
41	DE	Display enable pin from controller. Data Input Enable.
42	GND	Power ground.
43	DCLK	Sample clock. Data will be latched at the falling edge of DCLK.
44	GND	Power ground.
45	CS / ID1	Chip Select/ ID[4:1]These pins select LCM type.
46	SDIN / ID2	SPI Data/ ID[4:1]These pins select LCM type.
47	SCK / ID3	SPI Clock/ ID[4:1]These pins select LCM type.
48	DISPLAY	Display Enable (Hi Active) / ID[4:1]These pins select LCM type.
	CONTROL / ID4	
49	/RESET	Global Reset (Low Active).
50	GND	Power ground.

4-Wire Resistive Touch Screen (RTP) Interface

Pin No.	Symbol	Function
1	YU	Up side of touch panel.
2	XR	Right side of touch panel.
3	YD	Bottom side of touch panel.
4	XL	Left side of touch panel.



2.2.1 Refer Initial Code

HX8238-D register configuration is recommended to use the default value (HSP=0, VSP=0, CKP=0, DEP=0).

Note:

HSP: When HSP=0, HS(HSYNC) is negative polarity. When HSP=1, HS(HSYNC) is positive polarity.

VSP: When VSP=0, VS(VSYNC) is negative polarity. When VSP=1, VS(VSYNC) is positive polarity.

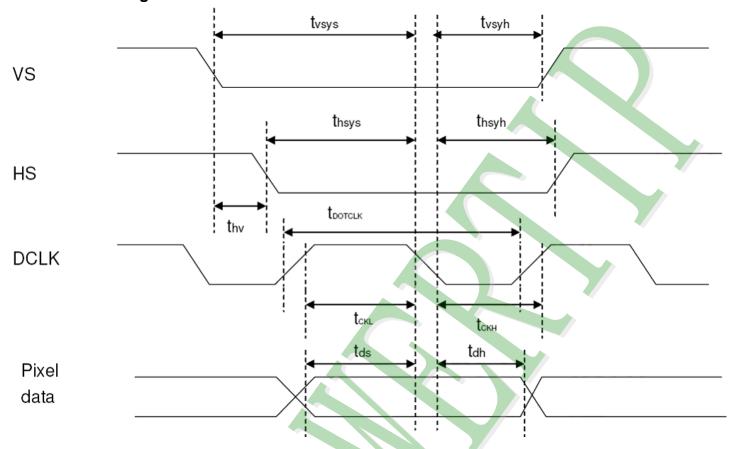
CKP: When CKP=0, data is latched in DCLK falling edge. When CKP=1, data is latched in DCLK rising edge.

DEP: When DEP=0, DE is negative polarity active. When DEP=1, DE is positive polarity active.





2.3 Timing Characteristics 2.3.1 Pixel timing for HX8238-D



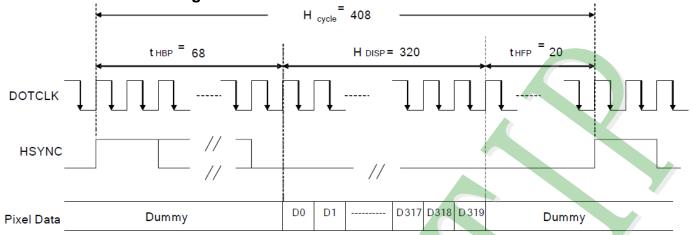
Characteristics	Symbol	Min	Тур	Max	Unit
DCLK Frequency	fDCLK		6.5	10	MHz
DCLK Period	tDCLK	100	154	-	ns
Vertical Sync Setup Time	tvsys	20		-	ns
Vertical Sync Hold Time	tvsyh	20	1	•	ns
Horizontal Sync Setup Time	thsys	20	1	-	ns
Horizontal Sync Hold Time	thsyh	20	1	•	ns
Phase difference of Sync Signal Falling Edge	thv	1	1	240	tDCLK
DCLK Low Period	tCKL	50	1	-	ns
DCLK High Period	tCKH	50	1	•	ns
Data Setup Time	tds	12	1	1	ns
Data hold Time	tdh	12	-	-	ns
Reset pulse width	tRES	10	-	-	us

Note: External clock source must be provided to DOTCLK pin of HX8238-A. The driver will not operate if absent of the clocking signal.

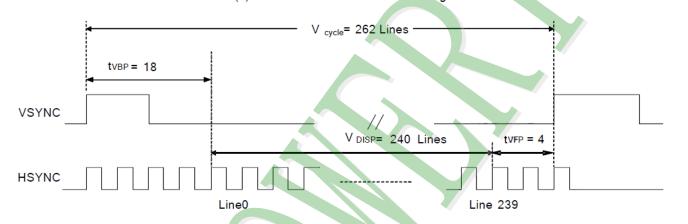
Pixel timing



2.3.2 Data transaction timing for HX8238-D



(a) Horizontal Data Transaction Timing



(b) Vertical Data Transaction Timing

Data transaction timing in parallel RGB (24 bit) interface (SYNC mode)

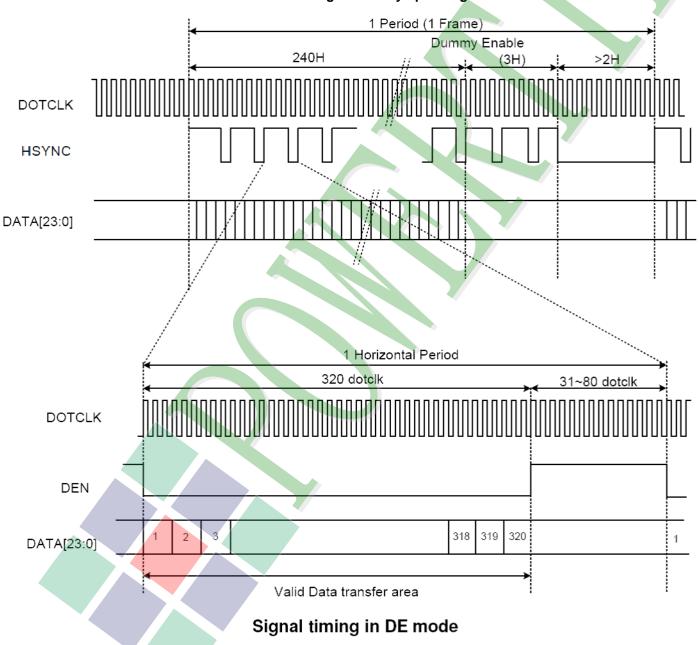
Characteristics	Symbol	Min	Тур	Max	Unit
DOTCLK Frequency	fDOTCLK	-	6.5	10	MHz
DOTCLK Period	tDOTCLK	100	154	-	ns
Horizontal Frequency (Line)	fH	-	14.9	22.35	KHz
Vertical Frequency (Refresh)	fV	-	60	90	Hz
Horizontal Back Porch	tHBP	-	68	-	tDOTCLK
Horizontal Front Porch	tHFP	-	20	-	tDOTCLK
Horizontal Data Start Point	tHBP	-	68	-	tDOTCLK
Horizontal Blanking Period	tHBP + tHFP	-	88	-	tDOTCLK
Horizontal Display Area	HDISP	1	320	-	tDOTCLK
Horizontal Cycle	Hcycle	1	408	450	tDOTCLK
Vertical Back Porch	tVBP	1	18	-	Lines
Vertical Front Porch	tVFP	1	4	-	Lines
Vertical Data Start Point	tVBP	1	18	-	Lines
Vertical Blanking Period	tVBP + tVFP	-	22	-	Lines
Vertical Display Area	VDISP	-	240	-	Lines
Vertical Cycle	Vcycle	-	262	350	Lines

Data transaction timing in normal operating mode



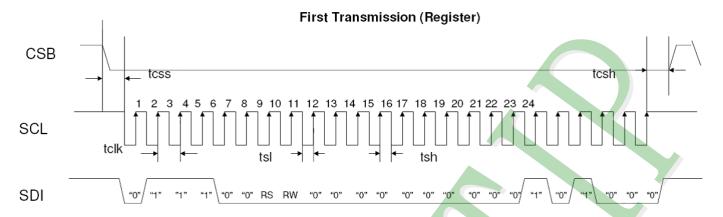
Characteristics	Symbol	Min.	Тур.	Max.	Unit
DOTCLK Frequency	fDOTCLK	- /	6.5	10	MHz
DOTCLK Period	tDOTCLK	100	154	-	ns
Horizontal Blanking Period	tHBP + tHFP	52	88	180	tDOTCLK
Horizontal Display Area	HDISP		320	-	tDOTCLK
Horizontal Cycle	Hcycle	372	408	500	tDOTCLK
Vertical Blanking Period	tVBP + tVFP	2	-	47	Lines
Vertical Display Area	VDISP	-	240	<u> </u>	Lines
Vertical Cycle	Vcycle	242	-	287	Lines

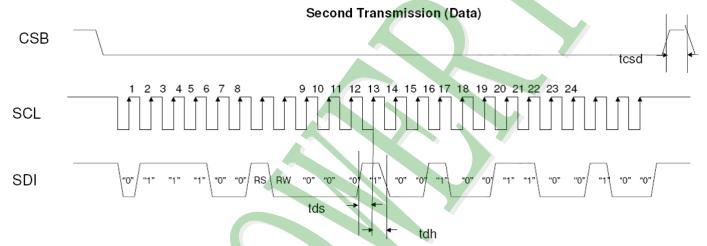
Data transaction timing in DE only operating mode





2.3.3 SPI Timing Characteristics for HX8238-D





Note: The example transmit "0x1264h" to register R28h. SPID connected to VSS.

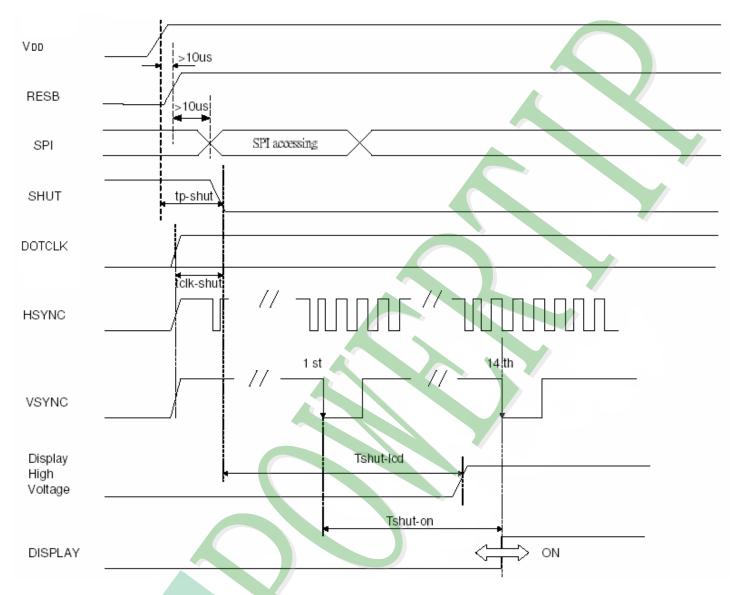
SPI interface timing diagram & transaction example

Characteristics	Symbol	Min	Тур	Max	Unit
Serial Clock Frequency	fclk	-	-	20	MHz
Serial Clock Cycle Time	tclk	50	-	-	ns
Clock Low Width	tsl	25	-	-	ns
Clock High Width	tsh	25	-	-	ns
Chip Select Setup Time	tess	0	-	-	ns
Chip Select Hold Time	tcsh	10	-	-	ns
Chip Select High Delay Time	tcsd	20	-	-	ns
Data Setup Time	tds	5	-	1	ns
Data Hold Time	tdh	10	-	-	ns

SPI timing



2.4 Power Sequence 2.4.1 Power up sequence



Characteristics	Symbol	Min	Тур	Max	Units
VDD on to falling edge of SHUT	tp-shut	1	-	-	us
DOTCLK	tclk-shut	1	-	-	clk
Falling edge of SHUT to LCD power on	tshut-lcd	•	,	128	ms
Falling edge of SHUT to display start		-	-	14	frame
- 1 line: 408 clk - 1 frame: 262 line -DOTCLK ≠ 6.5MHz	tshut-on	-	166	232.4	ms

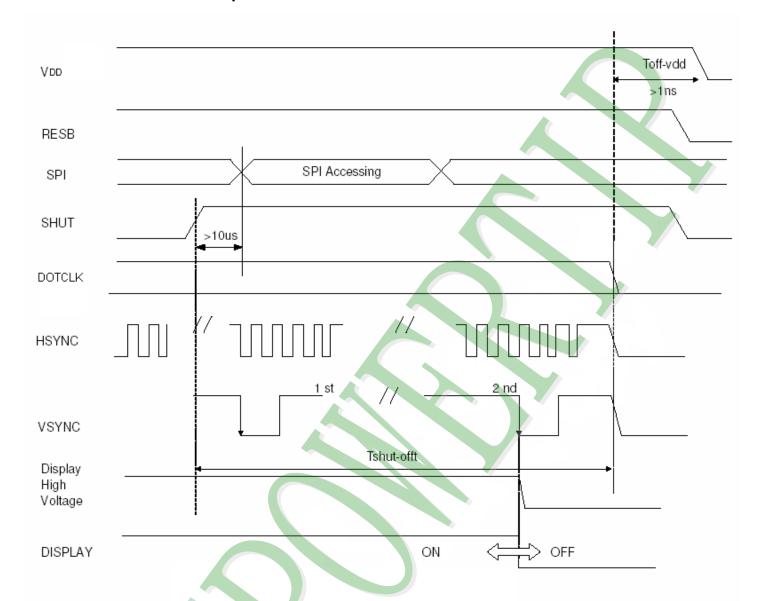
Note: It is necessary to input DOTCLK before the falling edge of SHUT.

Display starts at 10th falling edge of VSYNC after the falling edge of SHUT.

Interface PIN No. 48" Display control" have connected Inverters logic gates to the "SHUT" pin.



2.4.2 Power down sequence



Characteristics	Symbol	Min	Тур	Max	Uni
Rising edge of SHUT to display off		2	-	-	frame
- 1 line: 408 clk - 1 frame; 262 line - DOTCLK = 6.5MHz	tshut-off	33.4	1	1	ms
Input-signal-off to VDD off	toff-vdd	1	-	-	us

Note: DOTCLK must be maintained at lease 2 frames after the rising edge of SHUT.

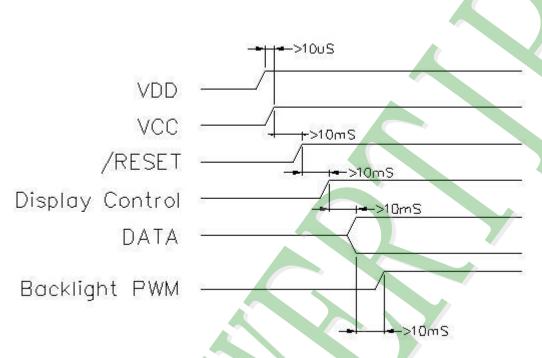
Display become off at the 2nd falling edge of VSYNC after the falling edge of SHUT.

If RESET signal is necessary for power down, provide it after the 2-frames-cycle of the SHUT period.

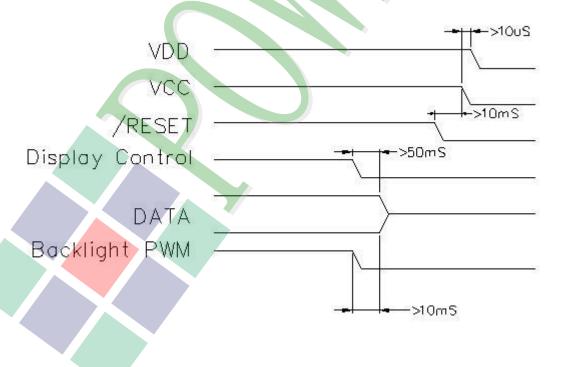


2.4.3 Power Timing Characteristics of Backlight

POWER ON



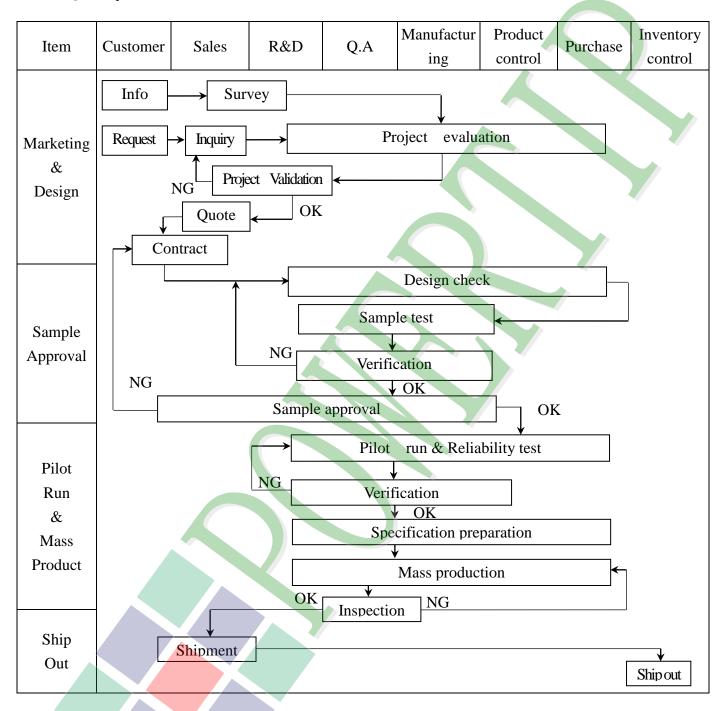
POWER OFF



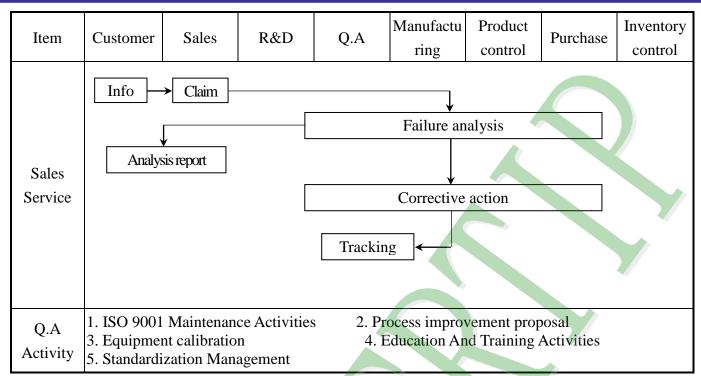


3. QUALITY ASSURANCE SYSTEM

3.1 Quality Assurance Flow Chart









3.2 Inspection Specification

Scope: The document shall be applied to TFT-LCD Module for 3, $5'' \sim 10''$ (Ver.B01).

◆Inspection Standard: MIL-STD-105E Table Normal Inspection Single Sampling Level Ⅱ.

◆Equipment : Gauge · MIL-STD · Powertip Tester · Sample

◆Defect Level: Major Defect AQL: 0.4; Minor Defect AQL: 1.5

♦OUT Going Defect Level: Sampling.

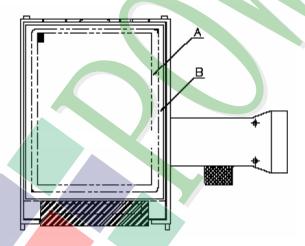
◆Standard of the product appearance test:

a. Manner of appearance test:

- (1). The test best be under 20W×2 fluorescent light, and distance of view must be at 30 cm.
- (2). The test direction is base on about around 45° of vertical line.



(3). Definition of area.



A area: viewing area

B area: Outside of viewing area

(4). Standard of inspection: (Unit: mm)



igspace Specification For TFT-LCD Module 3. 5" ~10":

emention For TT 1-DCD Module 9, 9 10 . (VI.D		
Item	Criterion	Level
	1. 1The part number is inconsistent with work order of production.	Major
Product condition	1. 2 Mixed product types.	Major
	1. 3 Assembled in inverse direction.	Major
Quantity	2. 1The quantity is inconsistent with work order of production.	Major
Outline dimension	3. 1 Product dimension and structure must conform to structure diagram.	
	4. 1 Missing line character and icon.	Major
	4. 2 No function or no display.	Major
Electrical Testing	4. 3 Display malfunction.	Major
	4. 4 LCD viewing angle defect.	Major
	4. 5 Current consumption exceeds product specifications.	Major
	Item Acceptance (Q'ty)	
Dot defect	Bright Dot ≤ 4	
Dot defect	Dot Dark Dot ≤ 5	
(Bright dot \	$\begin{array}{c c} \textbf{Defect} & \textbf{Joint Dot} & \leq 3 \end{array}$	
Dark dot)	Total ≤ 7	Minor
On -display 5. 1 Inspection	5. 1 Inspection pattern: full white, full black, Red, Green and	
	blue screens.	
	5. 2 It is defined as dot defect if defect area $>1/2$ dot.	
	5. 3 The distance between two dot defect ≥ 5 mm.	
	Product condition Quantity Outline dimension Electrical Testing Dot defect (Bright dot > Dark dot)	Product condition 1. 2 Mixed product types. 1. 3 Assembled in inverse direction. Quantity 2. 1The quantity is inconsistent with work order of production. Outline dimension 3. 1 Product dimension and structure must conform to structure diagram. 4. 1 Missing line character and icon. 4. 2 No function or no display. 4. 3 Display malfunction. 4. 4 LCD viewing angle defect. 4. 5 Current consumption exceeds product specifications. Dot defect (Bright dot bark dot) On -display 5. 1 Inspection pattern: full white, full black, Red, Green and blue screens. 5. 2 It is defined as dot defect if defect area > 1/2 dot.



igspace Specification For TFT-LCD Module 3. 5" ~10":

NO	Item	Criterion	
		6. 1 Round type (Non-display or display) :	
		Dimension (diameter : Φ)	
	Black or white dot \ scratch \	$\Phi \le 0.25$ Ignore	>
	contamination	$0.25 < \Phi \leq 0.50$ Ignore	
	Round type	$\Phi > 0.50$	
	$X \xrightarrow{Y} Y$	Total 5	
06	$\Phi = (x+y)/2$	6. 2 Line type(Non-display or display) :	Minor
	¥ (X y) / 2	Acceptance (Q'ty)	
	Line type	Length (L) Width (W) A area B area	
	✓ † W	$ \begin{array}{c ccccccccccccccccccccccccccccccccccc$	
	L	L \leq 5.0 0.05 < W \leq 0.10 2 Ignore	
		W >0.10 As round type	
		Total 5	
		Dimension (diameter : 4) Acceptance (Q'ty)	
		Dimension (diameter : Φ) Acceptance (Q ty) A area B area	
		$\Phi \leq 0.25$ Ignore	
07	Polarizer Bubble	$0.25 < \Phi \leqq 0.50 \qquad \qquad 4$	Minor
	Duoble	$0.50 < \Phi \le 0.80$ 1 Ignore	
		$\Phi > 0.80$	
		Total 5	



◆Specification For TFT-LCD Module 3. 5″~10″:

NO	Item	Criterion		Level
		Z: The thickness of crack	Y : The width of crack. V : terminal length a : LCD side length	
		8. 1 General glass chip: 8. 1.1 Chip on panel surface and cra	ick between panels:	
08	The crack of glass	SP Z (OK)	Z X SP [NG]	Minor
		Seal width Z	Y	
		X Y	z	
		≤ a Crack can't enter viewing area	≦1/2 t	
		≤ a Crack can't exceed the half of SP width.	$1/2 t < Z \leq 2 t$	



◆Specification For TFT-LCD Module 3. 5″ ~10″:

NO	Item	Criterion	Level
		Symbols: X: The length of crack Z: The thickness of crack t: The thickness of glass Y: The width of crack. W: terminal length a: LCD side length	
		8. 1. 2 Corner crack:	
		$\leq 1/5$ a Crack can't exceed the half of SP width. $1/2$ t $<$ Z ≤ 2 t	
08	The crack of glass	8.2 Protrusion over terminal:	Minor
		8.2.1 Chip on electrode pad:	
		W X	
		$ \begin{array}{c cccc} X & Y & Z \\ \hline Front & \leq a & \leq 1/2 \text{ W} & \leq t \\ \end{array} $	
		$\begin{array}{c ccccccccccccccccccccccccccccccccccc$	



◆Specification For TFT-LCD Module 3. 5″~10″:

NO	Item	Criterion	
NO 08	The crack of glass	Symbols: X: The length of crack Z: The thickness of crack t: The thickness of glass 8. 2. 2 Non-conductive portion: X: The width of crack. W: terminal length a: LCD side length 8. 2. 2 Non-conductive portion: X: The width of crack. W: terminal length a: LCD side length 8. 2. 2 Non-conductive portion: X: X	Level



◆Specification For TFT-LCD Module 3. 5″ ~10″:

NO	Item	Criterion	Level
09	Backlight elements	9. 1 Backlight can't work normally.	Major
		9. 2 Backlight doesn't light or color is wrong.	Major
		9. 3 Illumination source flickers when lit.	Major
10	General	10. 1 Pin type · quantity · dimension must match type in structure diagram.	Major
		10. 2 No short circuits in components on PCB or FPC.	Major
		10. 3 Parts on PCB or FPC must be the same as on the production characteristic chart .There should be no wrong parts , missing parts or excess parts.	Major
		10. 4 Product packaging must the same as specified on packaging specification sheet.	Minor
		10. 5 The folding and peeled off in polarizer are not acceptable.	Minor
		10. 6 The PCB or FPC between B/L assembled distance(PCB or FPC) is ≤1.5 mm.	Minor



4. RELIABILITY TEST

4.1 Reliability Test Condition

4.	Reliability lest Colluition , ,		
NO.	TEST ITEM	TEST CONDITION	
1	High Temperature Storage Test	Keep in +80 ±2°C 96 hrs Surrounding temperature, then storage at normal condition 4hrs.	
2	Low Temperature Storage Test	Keep in −30 ±2°C 96 hrs Surrounding temperature, then storage at normal condition 4hrs.	
3	High Temperature / High Humidity Storage Test	Keep in +60°C / 90% R.H duration for 96 hrs Surrounding temperature, then storage at normal condition 4hrs. (Excluding the polarizer)	
4	Temperature Cycling Storage Test	$-30^{\circ}\text{C} \rightarrow +25^{\circ}\text{C} \rightarrow +80^{\circ}\text{C} \rightarrow +25^{\circ}\text{C}$ $(30\text{mins}) (5\text{mins}) (5\text{mins})$ 10 Cycle Surrounding temperature, then storage at normal condition 4hrs.}	
5	ESD Test	Air Discharge: Apply 2 KV with 5 times Discharge for each polarity +/- 1. Temperature ambiance : 15° C $\sim 35^{\circ}$ C 2. Humidity relative : $30\% \sim 60\%$ 3. Energy Storage Capacitance(Cs+Cd) $150 \text{pF} \pm 10\%$ 4. Discharge Resistance(Rd) : $330 \Omega \pm 10\%$ 5. Discharge, mode of operation : Single Discharge (time between successive discharges at least 1 sec) (Tolerance if the output voltage indication : $\pm 5\%$)	
6	Vibration Test (Packaged)	 Sine wave 10~55 Hz frequency (1 min) The amplitude of vibration :1. 5 mm Each direction (X \cdot Y \cdot Z) duration for 2 Hrs 	
7	Drop Test (Packaged)	Packing Weight (Kg) 0 ~ 45. 4 122 45. 4 ~ 90. 8 76 90. 8 ~ 454 61 Over 454 46	
		Drop direction: **1 corner / 3 edges / 6 sides each 1 times	



5. PRECAUTION RELATING PRODUCT HANDLING

5.1 SAFETY

- 5.1.1 If the LCD panel breaks, be careful not to get the liquid crystal to touch your skin.
- 5.1.2 If the liquid crystal touches your skin or clothes, please wash it off immediately by using soap and water.

5.2 HANDLING

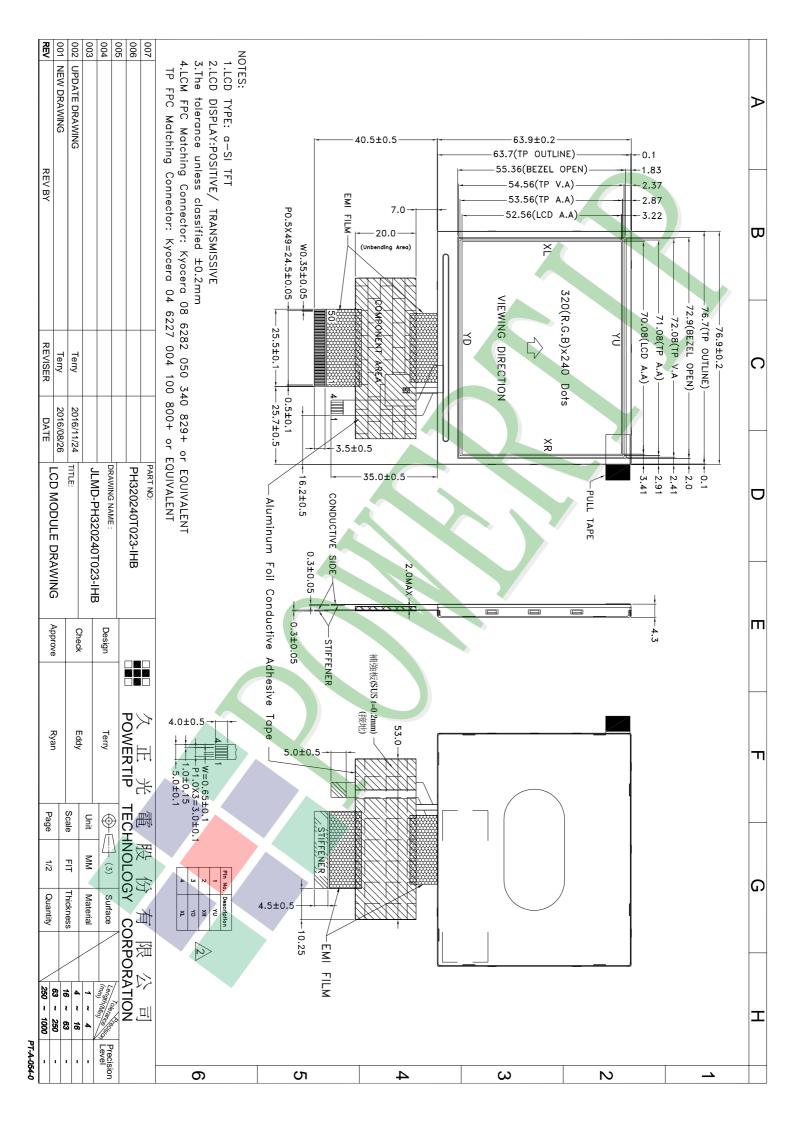
- 5.2.1 Avoid any strong mechanical shock which can break the glass.
- 5.2.2 Avoid static electricity which can damage the CMOS LSI—When working with the module, be sure to ground your body and any electrical equipment you may be using.
- 5.2.3 Do not remove the panel or frame from the module.
- 5.2.4 The polarizing plate of the display is very fragile. So , please handle it very carefully, do not touch , push or rub the exposed polarizing with anything harder than an HB pencil lead (glass , tweezers , etc.)
- 5.2.5 Do not wipe the polarizing plate with a dry cloth, as it may easily scratch the surface of plate.
- 5.2.6 Do not touch the display area with bare hands, this will stain the display area.
- 5.2.7 Do not use ketonics solvent & aromatic solvent. Use with a soft cloth soaked with a cleaning naphtha solvent.
- 5.2.8 To control temperature and time of soldering is $320 \pm 10^{\circ}$ C and 3-5 sec.
- 5.2.9 To avoid liquid (include organic solvent) stained on LCM

5.3 STORAGE

- 5.3.1 Store the panel or module in a dark place where the temperature is 25°C ± 5°C and the humidity is below 65% RH.
- 5.3.2 Do not place the module near organics solvents or corrosive gases.
- 5.3.3 Do not crush, shake, or jolt the module.

5.4 TERMS OF WARRANTY

- 5.4.1 Applicable warrant period
 - The period is within thirteen months since the date of shipping out under normal using and storage conditions.
- 5.4.2 Unaccepted responsibility
 - This product has been manufactured to your company's specification as a part for use in your company's general electronic products. It is guaranteed to perform according to delivery specifications. For any other use apart from general electronic equipment, we cannot take responsibility if the product is used in nuclear power control equipment, aerospace equipment, fire and security systems or any other applications in which there is a direct risk to human life and where extremely high levels of reliability are required.



Approve Check Contact Ver.002 LCM包裝規格書 LCM Packaging Specifications Ryan Eddy Terry JPKG-PH320240T023-IHB Documents NO. (For Tray) 1.包裝材料規格表 (Packaging Material): (per carton) 1Pcs Weight Item Model Dimensions (mm) Quantity Total Weight No. 76.9 X 63.9 X 4.3 1 成品 (LCM) PH320240T023-IHB 0.0425 252 10.71 2 多層薄膜(1)POF OTFILM0BA03ABA 19"X350X0.015 6 3 352 X 260 X 12.8 TRAY 盤 (2)Tray TYPH32024002BB 48 4.8 0.1 4 内盒(3)Product Box BX36627063ABBA 393 X 274 X 68 0.182 6 1.092 OTPLB00PL08ABA 0.0284 2 0.0568 保利龍板(4)Polylon board 550 X 393 X 20 外紙箱(5)Carton BX57041027CCBA 570 X 410 X 265 1 6 1.0 1.0 7 8 9 一整箱總重量 (Total LCD Weight in carton): 17.66 Kg±10% 3.單箱數量規格表 (Packaging Specifications and Quantity): (1)LCM quantity per box: no per tray x no of tray 7 42 6 (2) Total LCM quantity in carton: quantity per box x no of boxes 42 6 252 Use empty tray 空盤 (4)保利龍板 (1)多層薄膜 Polylon board **POF** Put products into the tray (2)TRAY 盤 Tray (5)外紙箱 Carton Tray stacking (3)内盒 Product Box 特 記 事 項 (REMARK) 4. Label Specifications: Detail B 依廠內標準作業 Tray 2 5.TRAY盤相疊時,需旋轉180度,請詳見B視圖 Rotate tray 180 degrees and place on top of stack.

Check the tray stack using Fig. B.